

AMENDMENT TO THE CLAIMS

1. (ORIGINAL) A glass-encapsulated light-emitting diode, comprising:

an LED bare chip;

a pair of electrodes each connected to said LED bare chip on an opposite side thereof;

a pair of leads each connected to said electrode and thereby arranged for said LED bare chip to be interposed between said leads along an electrode direction; and

a pair of metallic member each connected to an other end of said lead, wherein said LED bare chip including said electrodes and at least a part of said leads are integrally encapsulated with glass to produce said glass-encapsulated light-emitting diode, and metallic members are separately secured at both ends of said glass-encapsulated light-emitting diode.

2. (ORIGINAL) The glass-encapsulated light-emitting diode according to claim 1, wherein each lead is designed not to project out beyond said metallic member.

3. (CURRENTLY AMENDED) The glass-encapsulated light-emitting diode according to claim 1 ~~any one of claims 1-2~~, wherein glass for said glass-encapsulated light-emitting diode is composed of soft glass.

4. (CURRENTLY AMENDED) The glass-encapsulated light-emitting diode according claim 1 ~~to any one of claims 1-3~~, wherein solder-plating is applied on at least both outermost sides of said

glass-encapsulated light-emitting diode in an extending direction of said pair of leads.

5. (NEW) The glass-encapsulated light-emitting diode according to claim 2, wherein glass for said glass-encapsulated light-emitting diode is composed of soft glass.

6. (NEW) The glass-encapsulated light-emitting diode according to claim 2, wherein solder-plating is applied on at least both outermost sides of said glass-encapsulated light-emitting diode in an extending direction of said pair of leads.

7. (NEW) The glass-encapsulated light-emitting diode according to claim 3, wherein solder-plating is applied on at least both outermost sides of said glass-encapsulated light-emitting diode in an extending direction of said pair of leads.

8. (NEW) The glass-encapsulated light-emitting diode according to claim 5, wherein solder-plating is applied on at least both outermost sides of said glass-encapsulated light-emitting diode in an extending direction of said pair of leads.